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AUG 28 2007

Application No.: 11/791,410

Docket No.: JCLA12158

REMARKS**Present Status of the Application**

The Office Action dated 06/01/2007 has rejected claims 1, 2, 5, 7 and 17 under 35 U.S.C. 102(e), as being anticipated by Hashimoto (US 2003/0124773). Claims 3, 6, 8-10, 14-16, 18-20 were rejected under 35 U.S.C. 103(a), as being unpatentable over Hashimoto (US 2003/0124773). Claim 4 was rejected under 35 U.S.C. 103(a), as being unpatentable over Hashimoto (US 2003/0124773) in view of Segawa (US 2002/0057468). Claim 13 was rejected under 35 U.S.C. 103(a), as being unpatentable over Hashimoto (US 2003/0124773) in view of Glenn (US 6,266,197). In addition, claims 11-12 are objected to but would be allowable if rewritten in independent form including all of the limitations of the bas claim and any intervening claims.

Claims 1, 8 and 17 have been amended and claims 3-4 are canceled for clarification purposes. Supporting grounds can be found at least in figures 5-7. No new matter has been added to the application by the amendments made to the claims. This Amendment is promptly filed to place the above-captioned case in condition for allowance. After carefully considering the remarks set forth in this Office Action and the cited references, Applicants respectfully submitted that the presently pending claims are in condition for allowance. Reconsideration and withdrawal of the Examiner's rejection are requested.

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Discussions of the 102 and 103 rejections

Claims 1, 2, 5, 7 and 17 under 35 U.S.C. 102(e), as being anticipated by Hashimoto (US 2003/0124773). Claim 4 was rejected under 35 U.S.C. 103(a), as being unpatentable over Hashimoto (US 2003/0124773) in view of Segawa (US 2002/0057468).

Applicant has amended claim 1 with adding claim 4 into claim 1. The office action stated Hashimoto does not disclose a hard plate disposed on the other side of the flexible circuit board corresponding to the image sensing and process unit. Segawa discloses a camera module similar to that of Hashimoto and further discloses that additional components such as processing, chip components and connectors or "hard plate" can be placed on the opposite side of the circuit board (Fig. 1, para[0028]-[0029]). However, applicant respectfully submits Segawa does not teach that *a hard plate* is placed on the opposite side of the circuit board *corresponding to said image sensing and processing unit*. Please see Fig. 1 of the Segawa reference, Segawa just teaches a connector 4, chips 3 and signal processing IC 2 are disposed on the wiring board, and Segawa fails to teach *a hard plate* is placed on the opposite side of the circuit board *corresponding to said image sensing and processing unit* so as to enhance the mechanical strength.

For at least the foregoing reasons, Applicant respectfully submits that independent claim 1 patentably defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 2, 5-7 patentably define over the prior art as a matter of law, for at least the reason that these dependent claims contain all features of their respective independent claim.

In addition, the present application also provides an image sensing and processing unit as

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claim 17 recites.

17. A image sensing and processing unit, comprising:
a signal processing device;
an image sensing device stacked on and electrically connected to signal processing device;
and
a circuit board directly connected to at least one of said signal processing device and image sensing device.

In Fig. 1 of the Hashimoto reference, the optical chip 10 and the circuit board 70 are electrically connected to each other through the wiring 50. In Fig. 6 of the Hashimoto reference, the optical chip 10 and the chip 100 are electrically connected to the circuit board 70 through the wirings 50 and 116. However, in claim 17 of the present application, the circuit board is directly connected to said signal processing device and image sensing device. Hashimoto fails to teach the chip can be directly connected to the circuit board. Therefore, applicant respectfully submits that independent claim 17 patently defines over the prior art reference, and should be allowed.

Claims 3, 6, 8-10, 14-16, 18-20 were rejected under 35 U.S.C. 103(a), as being unpatentable over Hashimoto (US 2003/0124773).

Applicant has canceled claim 3. In addition, applicant submits that, as disclosed above, Hashimoto fail to teach or suggest each and every element of claim 1 and 17, from which claims 6 and 18-20 depend. Therefore, dependent claims 6 and 18-20 patently define over the prior art

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as a matter of law.

Moreover, the present application also provides a camera module as claim 8 recites.

8. A camera module, comprising:

a lens;

a holder having a lower portion and a bottom, said holder holding said lens;

an image sensing and processing unit including an image sensing device and an optional signal processing device stacked on and electrically connected to said image sensing device;

a plate holding said image sensing and processing unit and covering said bottom of said holder, said image sensing and processing unit being inside said lower portion of said holder; and

at least a flexible circuit board directly connected to said image sensing and processing unit

As above discussed, in Fig. 1 of the Hashimoto reference, the optical chip 10 and the circuit board 70 are electrically connected to each other through the wiring 50, and In Fig. 6 of the Hashimoto reference, the optical chip 10 and the chip 100 are electrically connected to the circuit board 70 through the wirings 50 and 116. However, in claim 8 of the present application, the flexible circuit board is directly connected to said image sensing and processing unit. Hashimoto fails to teach the chip can be directly connected to the circuit board. Therefore, applicant respectfully submits that independent claim 8 patently defines over the prior art reference, and should be allowed. For at least the same reasons, dependent claims 9-10 and 14-16 patently define over the prior art as a matter of law, for at least the reason that these dependent claims contain all features of their respective independent claim.

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Claim 13 was rejected under 35 U.S.C. 103(a), as being unpatentable over Hashimoto (US 2003/0124773) in view of Glenn (US 6,266,197).

Applicant submits that, as disclosed above, Hashimoto fails to teach or suggest each and every element of claims 8 from which claims 13 depend. Glenn cannot cure the deficiencies of Hashimoto. Therefore, independent claim 8 is patentable over Hashimoto and Glenn. For at the least the same reasons, their dependent claim 13 is also patentable.

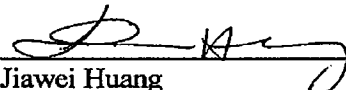
CONCLUSION

In view of the foregoing, it is believed that all pending claims are in proper condition for allowance. If the Examiner believes that a conference would be of value in expediting the prosecution of this application, he is cordially invited to telephone the undersigned counsel to arrange for such a conference.

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Respectfully submitted,
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